Abstract

This is a semiconductor device, a method of the same, a circuit board, and a flexible substrate that are easy to handle, enable quality assurance, and also enable batch connection of a flexible substrate to the electrodes of a semiconductor chip. A gap preservation member 16 is provided on a surface, of a flexible substrate 12, on which connection portions 24 to electrodes 14 of a semiconductor chip 10 are disposed. The semiconductor chip 10 and the flexible substrate 12 are arranged in a state in which the gap preservation member 16 is interposed therebetween. The connection portions 24 provided on the flexible substrate 12 are connected to the electrodes 14 of the semiconductor chip 10, and a molding material is injected to provide a stress absorption layer 26.

This Sheet Has Been Replaced

